

Application No. 10/667,369  
Amendment dated March 16, 2006  
After Final Office Action of December 16, 2005

Docket No.: 3313-1036P

**AMENDMENTS TO THE CLAIMS**

1-11. (Cancelled)

12. (Currently Amended) A heat-dissipating fin module comprising:

a heat-conductive base, which is installed on a heat-generating component of an electronic device;

a plurality of first heat-dissipating fins, which are vertically installed at intervals on one half of a first side of the heat-conductive base, each of the first heat-dissipating fins having an arc surface parallel to one another, and the space between adjacent first heat-dissipating fins forming a first airflow space for providing a curved airflow path;

a plurality of second heat-dissipating fins, which are vertically installed at intervals on the other half of said first side of the heat-conductive base, each of the second heat-dissipating fins having an arc surface parallel to one another but having curvature centers opposite to those of the first heat-dissipating fins, and the space between adjacent second heat-dissipating fins forming a second airflow space for providing a curved airflow path that does not cross the airflow path of the first airflow space;

at least one third heat-dissipating fin, which is vertically installed on the heat-conductive base in an outer region between the first heat-dissipating fins and the second heat-dissipating fins; and

wherein, the curvature centers of the first heat-dissipating fins and the second heat-dissipating fins are on a same line, the outermost first heat-dissipating fin and second heat-dissipating fin are shorter, and the third heat-dissipating fin is straight.

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13-17. (Cancelled)

18. (Original) The heat-dissipating fin module of claim 12, wherein the first heat-dissipating fins, the second heat-dissipating fins, and the third heat-dissipating fins are formed on the heat-conductive base by cutting and squeezing.

19. (New) The heat-dissipating fin module of claim 12, wherein an inlet of said first airflow space and an inlet of said second airflow space are on said first side and an outlet of said first airflow space and an outlet of said second airflow space are on a second side of the heat-conductive base, said first and second sides being opposite each other.